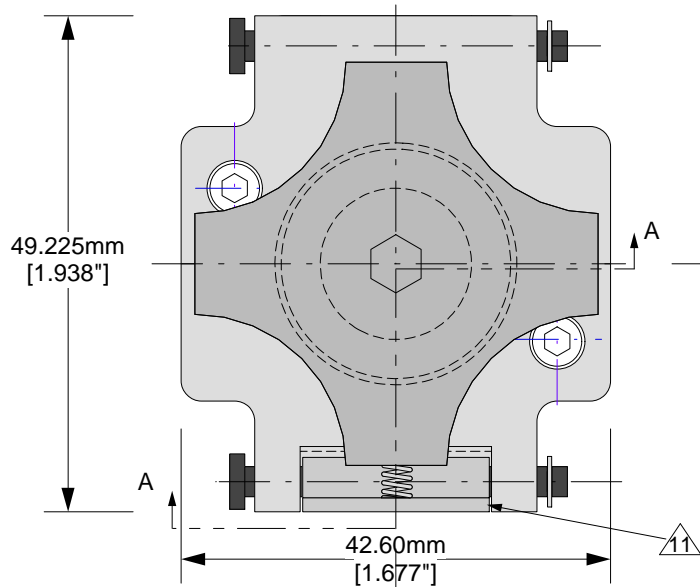
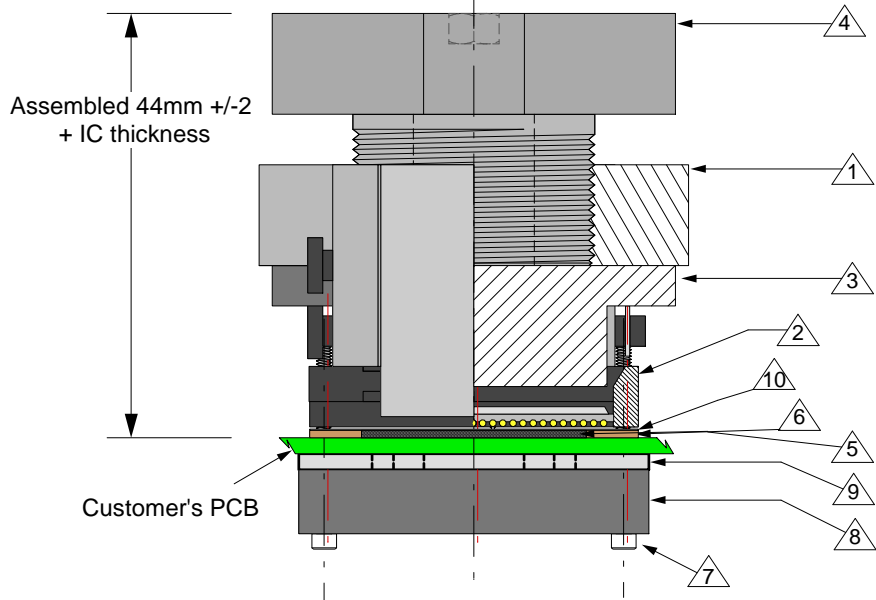


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

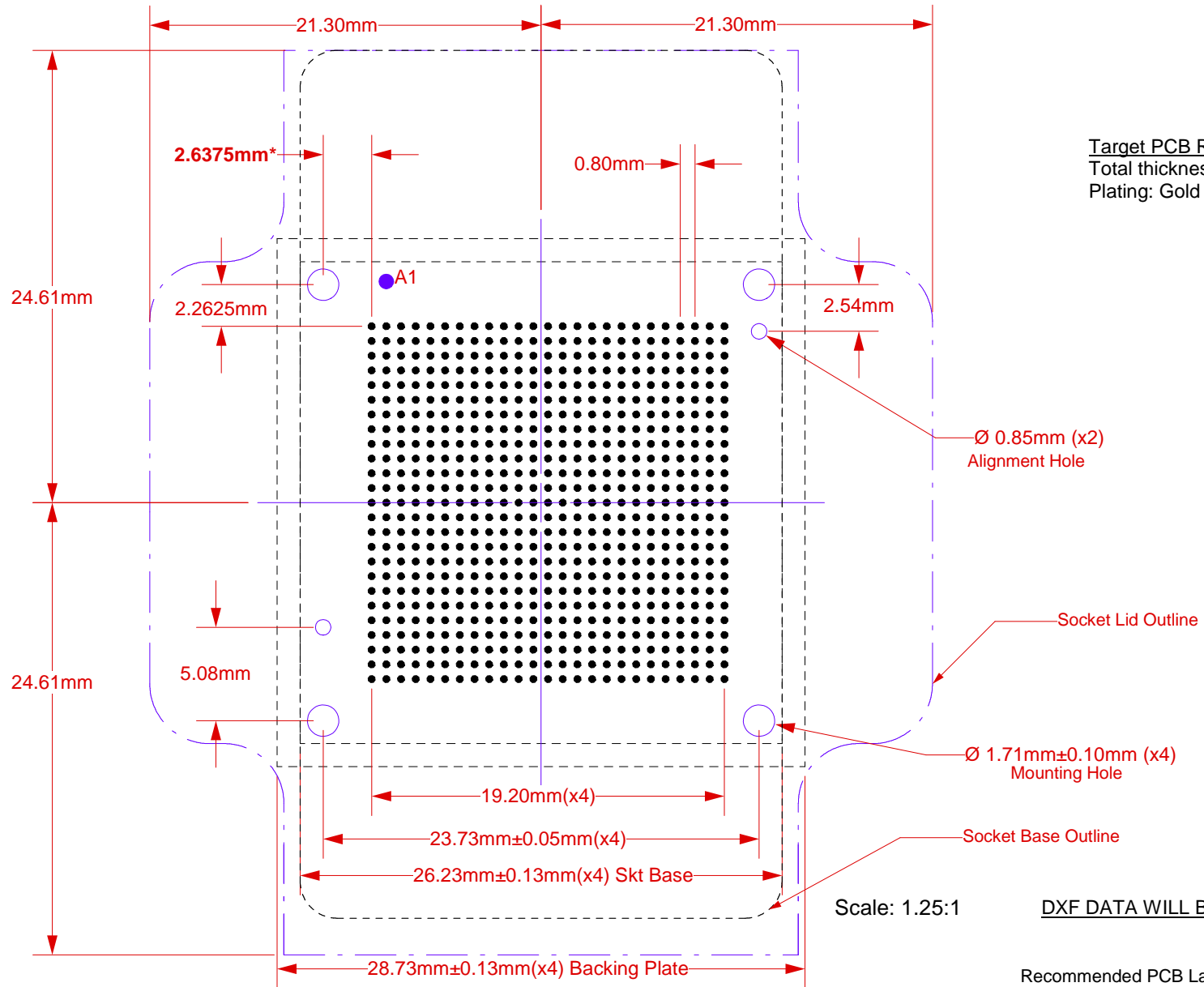
Materials:

- ① Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- ② Socket Base: Black anodized Aluminum. Height = 6 mm.
- ③ Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- ④ Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- ⑤ Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- ⑥ Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- ⑦ Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- ⑧ Backing Plate: Black anodized Aluminum
- ⑨ Insulation Plate: FR4/G10
- ⑩ Ball Guide: Kapton polyimide.
- ⑪ Latch: Black anodized Aluminum.

	CG-BGA-4005 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/16/10
		File: CG-BGA-4005 Dwg	Modified:	

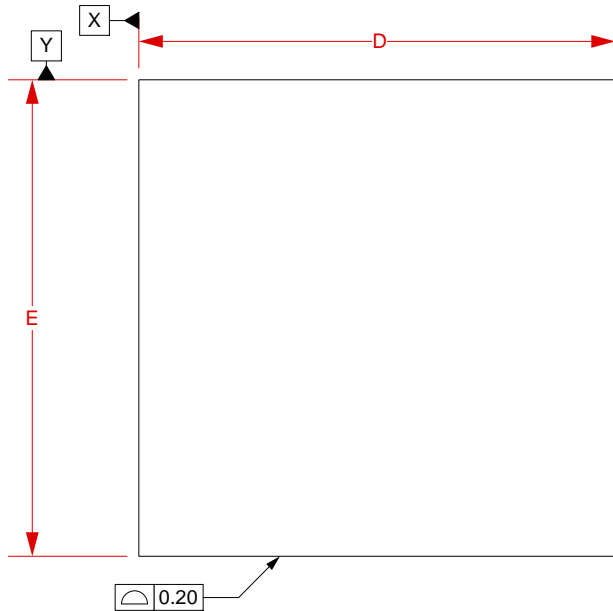
All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

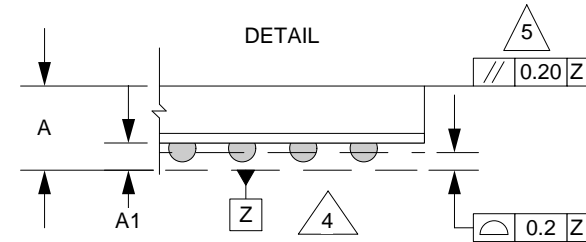
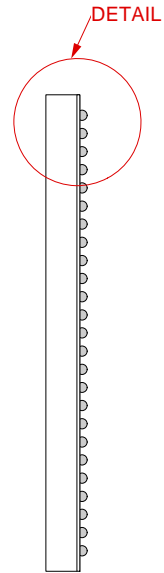


<p>CG-BGA-4005 Drawing</p>	<p>Status: Released</p>	<p>Scale: 3:1</p>	<p>Rev: A</p>
<p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>Drawing: Vinayak R</p>		<p>Date: 2/16/10</p>
<p>File: CG-BGA-4005 Dwg</p>		<p>Modified:</p>	

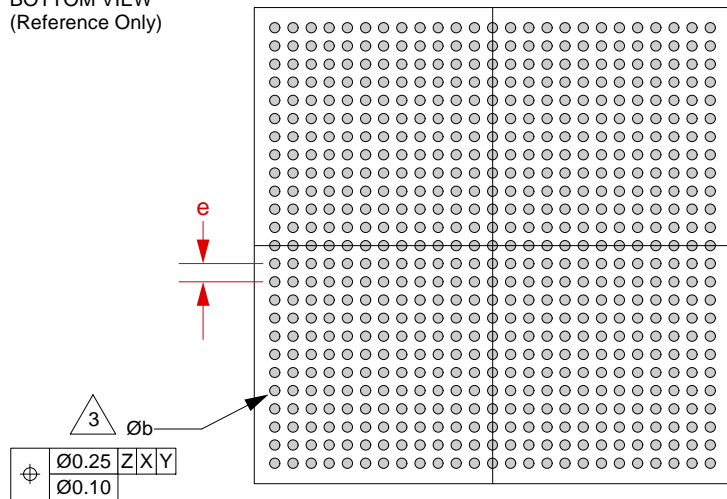
TOP VIEW
(Reference Only)



SIDE VIEW
(Reference Only)



BOTTOM VIEW
(Reference Only)



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.


3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

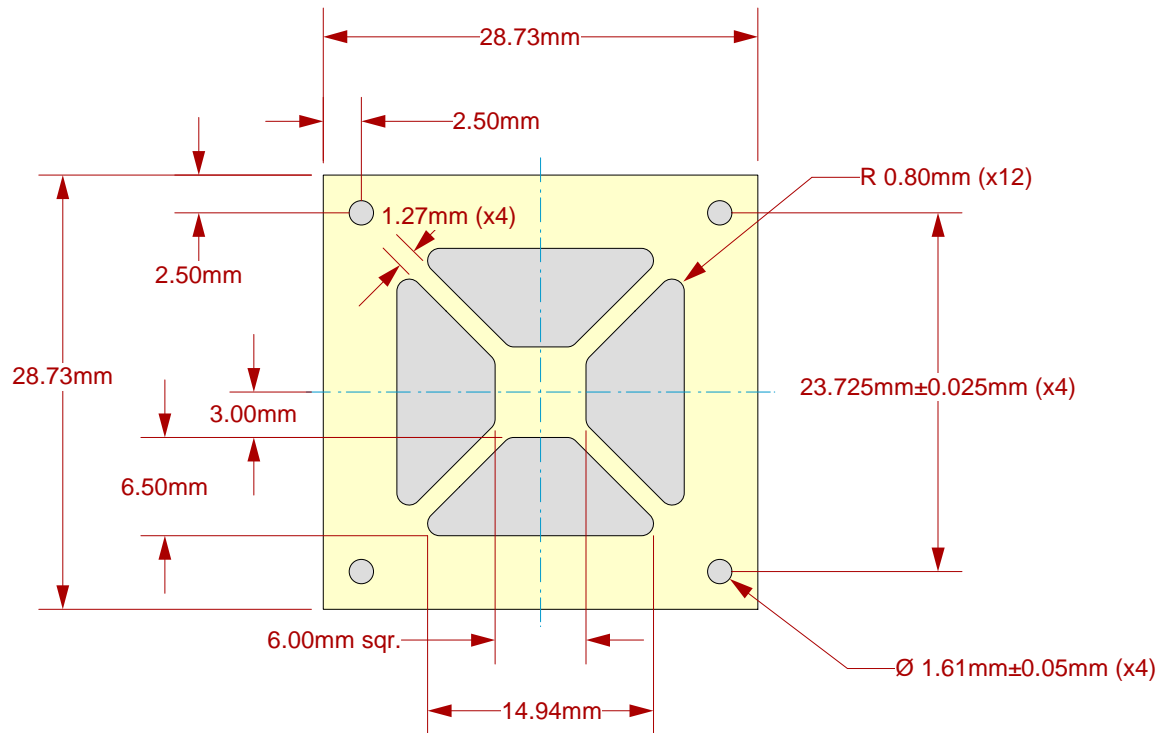
5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.70
A1	0.27	0.45
b		0.55
D	21.00 BSC	
E	21.00 BSC	
e	0.8 BSC	

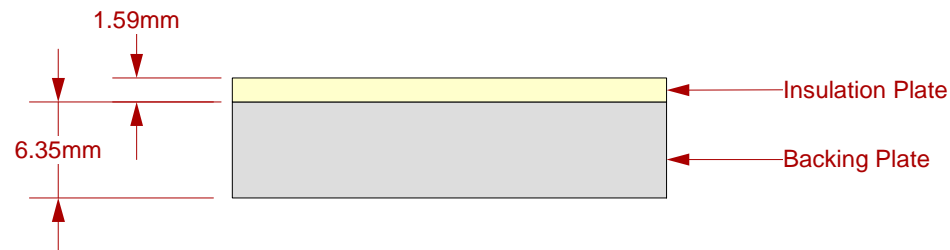
Array 25x25

	CG-BGA-4005 Drawing	Status: Released	Scale: -	Rev: A
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		File: CG-BGA-4005 Dwg	Modified:	

Top View




Side View

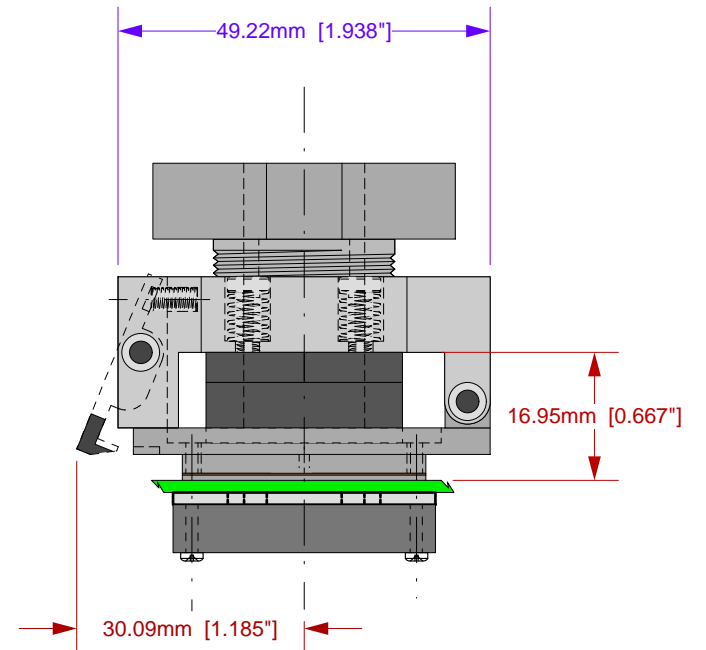
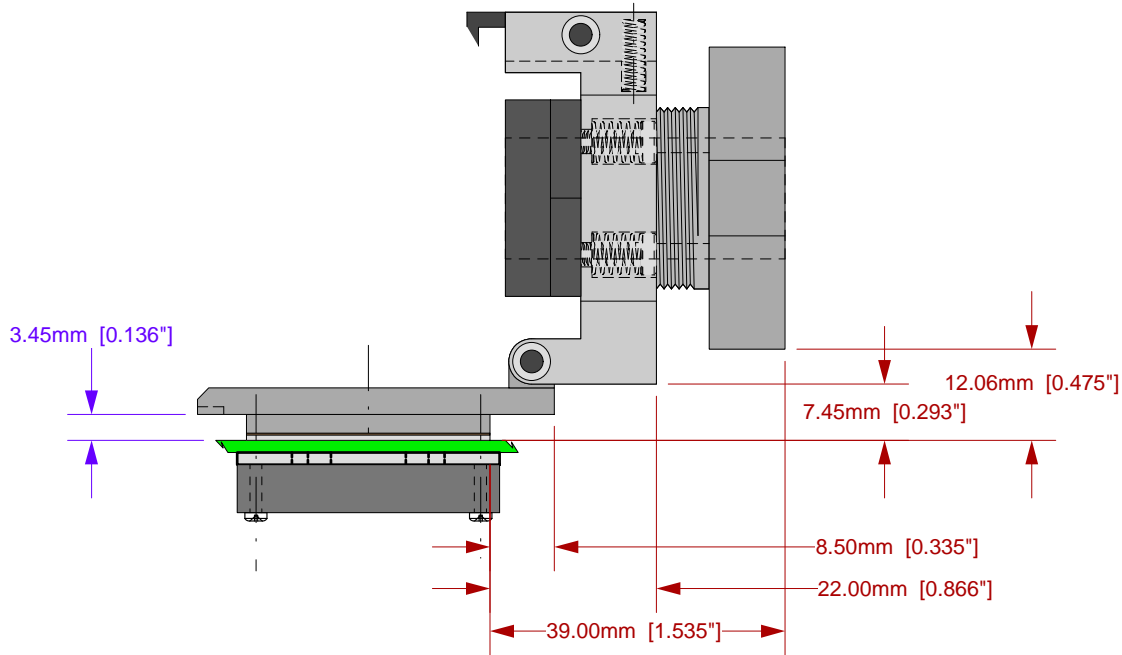
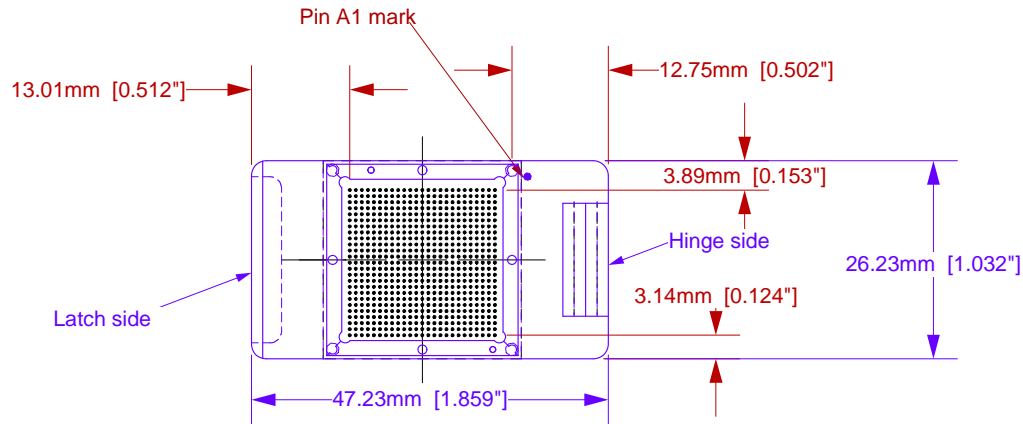



Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

	CG-BGA-4005 Drawing	Status: Released	Scale: 2:1	Rev: A
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		File: CG-BGA-4005 Dwg		Modified:

Top View of Socket Base



	CG-BGA-4005 Drawing	Status: Released	Scale: 1:1	Rev: A
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		File: CG-BGA-4005 Dwg		Modified: